

REMARKS**Amendment to the Claims**

Applicants have amended Claim 17 to correct an error in the originally filed text and more clearly define the invention. Support for the amendment can be found on page 9, lines 16-19, and in Fig. 1 as well as elsewhere in the Application.

Applicants have added new Claims 28-31 which are within the elected species. The new Claims are supported in the Application and no new matter has been added. For example, support for new Claim 28 can be found on page 9, lines 16-21, new Claim 29 is supported at page 8, lines 32-33, and new Claim 30 is supported at page 9, lines 10-15.

Claim rejections

The Examiner rejected Claims 17 and 21 under 35 U.S.C. §102(b) as being anticipated by Fraas et al. (US 5091018). Applicants respectfully traverse this rejection.

Fraas et al. discloses a process wherein a an insulating layer is formed over an upper surface of a substrate and a portion of the insulating layer is then removed after which the exposed portion of the substrate with a p-type dopant (col. 6, lines 36-62). In contrast, Claim 17, as amended, specifies a surface coating disposed over a first layer of a substrate which substrate is doped with a first dopant and which first layer is doped with a second dopant of opposite conductivity from the first dopant. Fraas et al. does not disclose a process wherein a surface coating is disposed as recited in Claim 17 and, therefore, Fraas et al. does not anticipate Claims 17 and 21.

The Examiner rejected Claims 18-20 under 35 U.S.C. §103(a) as being unpatentable over Fraas et al. (US 5091018) in view of Rittner (US 4135950). Applicants respectfully traverse this rejection because Fraas et al. and Rittner do not teach or suggest all of the features of the Claims as amended.

As noted above, the surface coating (64, Fig. 8A) of Fraas et al. is not disposed over a doped first layer as recited in the rejected Claims. Rittner does not disclose the feature of disposing a surface coating over a doped first layer. Nor does Rittner teach or suggest such a feature. Because neither Fraas et al. nor Rittner disclose such a feature, the rejected Claims are patentable over the cited references.

With respect to Claim 19, in addition to the reasons above, Rittner does not teach or suggest removing texture from the back surface of the substrate. Rittner specifies that the back surface of the substrate is masked prior to etching to protect it from etching (col. 2, lines 18-21). The precise etching parameters are critical to Rittner's disclosure (col. 2, lines 56-59) and, therefore, one of skill in the art is led away from modifying the etching process of Rittner to achieve Applicants' etched back surface and subsequent removal of the etching from the back surface.

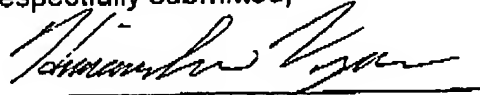
Because the combination of Fraas et al. and Rittner do not teach or suggest all of the limitations of the Claims as amended, Applicants respectfully request that the Examiner withdraw this rejection.

For the reasons above, Applicants believe that the pending Claims 17-21 and 28-30 are in condition for allowance. Applicants appreciate the Examiner's reconsideration of this matter.

If the Examiner has any question regarding this paper, the Examiner is encouraged to contact Applicants' attorney at the Examiner's convenience.

Correspondence Address:
BP America Inc.
Docket Clerk, Law Department, M.C. 5 East
4101 Winfield Road
Warrenville, Illinois 60555

Respectfully submitted,



Himanshu A. Vyas
Agent for the Applicant(s)
Registration Number 52,331
(630) 821-2443